

Lunar Reconnaissance Orbiter

Thermal System Specification

September 15, 2006

LRO GSFC CMO

October 10, 2006

RELEASED



National Aeronautics and
Space Administration

**Goddard Space Flight Center
Greenbelt, Maryland**

CHECK WITH LRO DATABASE AT:
<https://lunarngin.gsfc.nasa.gov>
TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

CM FOREWORD

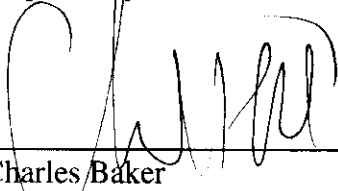
This document is a Lunar Reconnaissance Orbiter (LRO) Project Configuration Management (CM)-controlled document. Changes to this document require prior approval of the applicable Configuration Control Board (CCB) Chairperson or designee. Proposed changes shall be submitted to the LRO Project CM Office (CMO), along with supportive material justifying the proposed change. Changes to this document will be made by complete revision.

Questions or comments concerning this document should be addressed to:

LRO Project Configuration Management Office
Mail Stop 451
Goddard Space Flight Center
Greenbelt, Maryland 20771

Signature Page

Prepared by:



Charles Baker
LRO Thermal Systems Lead
GSFC/NASA, Code 545

9/15/06
Date

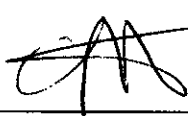
Reviewed by:



David Everett
LRO Mission Systems Engineer
GSFC/599

9/15/06
Date

Approved by:



Craig Tooley
LRO Project Manager
GSFC/NASA, Code 431

9/15/2006
Date

LUNAR RECONNAISSANCE ORBITER PROJECT**DOCUMENT CHANGE RECORD**

Sheet: 1 of 1

REV LEVEL	DESCRIPTION OF CHANGE	APPROVED BY	DATE APPROVED
Rev -	Released per 431-CCR-000022	C. Tooley	11/17/2005
Rev A	Released per 431-CCR-000105	C. Tooley	6/7/2006
Rev B	Released per 431-CCR-000225	C. Tooley	9/15/2006

CHECK WITH LRO DATABASE AT:
<https://lunarngin.gsfc.nasa.gov>
TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

List of TBDs/TBRs

Item No.	Location	Summary	Ind./Org.	Due Date
1	Section 1.4.1, 2.2, and 3.3	Provide document numbers to replace TBDs for Specific Thermal Hardware Specs and General Thermal Hardware Specs	C. Baker/ GSCF	8/1/2006
2	Section 1.4.2	Provide document number to replace TBD for LRO Thermal Balance/Thermal Vacuum Test Plan	C. Baker/ GSCF	8/1/2006
3	Table 2-3	Provide number of ST Internal Telemetry	J. Simpson/ GSFC	8/1/2006
4	Table 2-3	Provide number of TT&C Internal Telemetry Points	A. Rodriguez- Arroyo/ GSFC	8/1/2006
3	Section 3.3.6	Operational versus survival heaters on GYRO located on Essential Heater Bus is TBR.	C. Baker/ GSCF	8/1/2006
4	Section 5.2	Thermal Coatings Table has TBDs	W. Peters/ GSFC	12/1/2006

CHECK WITH LRO DATABASE AT:
<https://lunarngin.gsfc.nasa.gov>
 TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

TABLE OF CONTENTS

	<u>Page</u>
1.0 Scope.....	1-1
1.1 General.....	1-1
1.2 Purpose.....	1-1
1.3 Responsibility	1-1
1.4 Documents	1-1
1.4.1 Applicable Documents.....	1-1
1.4.2 Reference Documents	1-2
2.0 Temperture Requirements.....	2-1
2.1 Types of Temperature Limits.....	2-1
2.2 Location of Flight Telemetry	2-1
2.3 Flight Interface Design Temperature Limits.....	2-2
2.4 Temporal Gradient Requirements.....	2-6
2.5 Spatial Gradient Requirements	2-6
2.6 Turn On Temperature and Survival	2-7
2.7 Allocation of Spacecraft Monitored Temperature Sensors.....	2-7
3.0 Thermal Power.....	3-12
3.1 General heater circuit Requirements.....	3-12
3.2 Thermal Dissipated Power Per Mission Mode	3-12
3.3 Spacecraft Controlled Thermal Control Heater Power	3-12
3.3.1 Instrument Operational Heater Power Description.....	3-12
3.3.2 Spacecraft Operational Thermal Control Heat Power Description.....	3-14
3.3.3 Tight Bandwidth Command and Data Handling and Software Controlled Heater	3-14
3.3.4 Propulsion System Heaters Primary and Redundant Description.....	3-15
3.3.5 Deployment Heaters Description.....	3-15
3.3.6 Essential Heater Description.....	3-15
3.3.7 Instrument Survival Heaters Description.....	3-15
3.4 Spacecraft Heater Allocation	3-16
3.5 Instrument Heater Allocation (Wired to Spacecraft Switch).....	3-16
3.6 Instrument Heater Allocation (Controlled by Components/ Instruments).....	3-17
4.0 Multi-Layer Insulation Blankets	4-1
4.1 Outer Blanket Coating	4-1
4.2 Multi-Layer Insulation Blanket Grounding	4-1
4.3 Multi-Layer Insulation Blanket Documentation.....	4-1
4.4 Attachment of Multi-Layer Insulation Blankets	4-1
5.0 Thermal Analysis	5-1
5.1 Environmental Conditions	5-1
5.1.1 Thermal Conditions	5-1
5.1.2 Payload Fairing Ascent Pressure Profile.....	5-2

5.2	Thermal Coatings.....	5-2
5.3	Hot and Cold Bias of Power	5-4
5.4	Mission Modes.....	5-4
5.5	Thermal Model Margin.....	5-4
5.6	Thermal Modeling Scope.....	5-4
5.7	Thermal Analysis Documentation	5-5
6.0	Component and Orbiter Integration and Test.....	6-1
6.1	Component Thermal Cycling Requirement	6-1
6.2	Model Documentation	6-1
6.3	Component Thermal Test Model	6-1
6.4	Component Thermal Test Documentation.....	6-1
6.5	Thermal Model Correlation	6-1
6.6	Reduced Model	6-2
6.7	In-Air Thermal Control.....	6-2
6.8	Orbiter Thermal Vacuum/Balance Levelness and Orientation Requirements.....	6-2
6.9	Lunar Reconnaissance Orbiter Coordinate System	6-2
6.10	Test Heaters	6-2
6.11	Test Sensors	6-3
Appendix A. Abbreviations and Acronyms.....		1

LIST OF FIGURES

<u>Figure</u>	<u>Page</u>
Figure 5-1. Delta II-Like Fairing Pressure.....	5-2
Figure 6-1. LRO Coordinate System Definition.....	6-3

LIST OF TABLES

<u>Table</u>	<u>Page</u>
Table 2-1a. Spacecraft Interface Temperature Range.....	2-2
Table 3-1. Component Thermal Power Dissipations and Thermal Mission Modes.....	3-13
Table 3-3. Instrument Control Heater Power Allocations on the SC Instrument Operational Bus	3-16
Table 3-4. Instrument Control Heater Power Allocations	3-18
Table 5-1. LRO Solar Constant and Albedo Factor.....	5-1
Table 5-2. LRO Lunar Infrared.....	5-1
Table 5-3. LRO Thermal Coatings	5-2

1.0 SCOPE

1.1 GENERAL

This General Subsystem Thermal Specification defines and controls the top level thermal requirements for all components on the Lunar Reconnaissance Orbiter (LRO) spacecraft (SC). The specification places requirements on both sides of the SC-to-component interface to insure mission thermal safety. More details are controlled at lower level specifications such as the Thermal Interface Control Documents (ICD) specified in Section 4.1. This document outlines:

- a. Temperature Requirements
- b. Bounding Environmental Parameters
- c. Thermal Test Requirements
- d. Thermal Analysis Requirements (bounding inputs and required outputs)
- e. Thermal Report Requirements
- f. Component Thermal Hardware Drawings and Diagrams Requirements
- g. Instrument Allocated Operational and Survival Heater Power

1.2 PURPOSE

The purpose of this specification is to clearly define what is expected of every temperature sensitive component to be flown on LRO and the LRO thermal control system to satisfy that the component is safe to fly on LRO. This document is focused on the thermal interface to the SC but also requires that analysis be performed to show thermal safety throughout the powered component during all mission modes.

1.3 RESPONSIBILITY

The Goddard Space Flight Center (GSFC) has the final responsibility for the LRO mission, the Orbiter, its subsystems, and any requirements specifically assigned to LRO in this document.

LRO systems engineering and project management have the ultimate authority to specify thermal requirements. This document shall be the vehicle by which changing thermal requirements are tracked.

1.4 DOCUMENTS

1.4.1 Applicable Documents

The following documents form a part of this Specification to the extent specified herein:

431-OPS-000042	Lunar Reconnaissance Orbiter Mission Concept of Operations
431-RQMT-000092	Lunar Reconnaissance Orbiter Thermal Math Model Requirements
431-SPEC-000008	Lunar Reconnaissance Orbiter Electrical Systems Specification
431-SPEC-000112	Lunar Reconnaissance Orbiter Technical Resource Allocations Specification

- 431-SPEC-**TBD** Lunar Reconnaissance Orbiter General Thermal Hardware Specification
- 431-SPEC-**TBD** Lunar Reconnaissance Orbiter Project <Specific> Thermal Hardware Specification

1.4.2 Reference Documents

- 431-ICD-000114 Lunar Reconnaissance Orbiter Camera Thermal Interface Control Document
- 431-ICD-000115 Lyman-Alpha Mapping Project Thermal Interface Control Document
- 431-ICD-000116 Diviner Lunar Radiometer Experiment Thermal Interface Control Document
- 431-ICD-000117 Lunar Orbiter Laser Altimeter Thermal Interface Control Document
- 431-ICD-000118 Cosmic Ray Telescope for Effects of Radiation Thermal Interface Control Document
- 431-ICD-000119 Lunar Exploration Neutron Detector Thermal Interface Control Document
- 431-PLAN-**TBD** Lunar Reconnaissance Orbiter Project Thermal Balance/Thermal Vacuum Test Plan
- 431-SPEC-000012 Lunar Reconnaissance Orbiter Mechanical Systems Specification
- GSFC-STD-7000 General Environmental Verification Standards (GEVS) for Flight Programs and Projects
- MIL-R-39009 General Specification for Resistors, Fixed, Wire-Wound (Power Type, Chassis Mounted)
- NASA GSFC S311-641 Switch, Thermostatic, Bimetallic, SPST, Narrow Differential, Hermetic
- NASA GSFC S311-P-079 Procurement Specification for Thermofoil Heaters
- 431-ICD-000159 Mini-RF to Spacecraft Thermal Interface Control Document

2.0 TEMPERATURE REQUIREMENTS

These requirements apply to all flight powered components. To clarify the language used, a brief discussion of temperature limits vocabulary will explain the different types of limits.

2.1 TYPES OF TEMPERATURE LIMITS

There are three sets of temperature limits associated with critical locations and the SC-to-instrument thermal interface locations, defined as follows:

- a. Survival Limits: The minimum and maximum non-operating temperatures that may be experienced without inflicting damage or permanent performance degradation. Components must demonstrate that they can operate properly in thermal vacuum after exposure to cold survival limits. Survival limits must be at least as wide as qualification temperature limits.
- b. Qualification Temperature Limits: The minimum and maximum over which the responsible hardware manager has proven the component works thru qualification. The Qualification limits are 10 C outside of the Flight Limits. Acceptance Limits are 5 C outside of the Flight Limits. Any component that may be considered for Acceptance testing must present the case to the LRO Thermal Systems Lead that the same design component has been qualified in a relevant environment for LRO. The responsible hardware manager shall induce the qualification temperature limits in thermal vacuum testing prior to delivery to verify that the hardware can operate and survive over the entire specified temperature range.
- c. Flight Operational Limits: The flight operational limits must be at least 10°C inside the qualification limits, except for actively controlled components. The flight operational limits are treated as an “allocation” in the sense that the responsible hardware manager commits to not exceed them by design.

2.2 LOCATION OF FLIGHT TELEMETRY

There shall be temperature limits on all flight telemetry points during all phases of monitoring. However, it is the responsibility of the Orbiter thermal subsystem to only manage telemetry and limits at thermal interfaces that are specified in ICDs or subordinate specifications. These locations are designated by applicable component mechanical interface drawings provided by the responsible hardware manager. This location may be where the component attaches to a SC module deck or on the outside of a mutually agreed up location of the component that shall be clearly defined. Inside box/ component locations are acceptable if installed by component development team and reflected in the appropriate electrical ICD. Within the component itself, there is likely to be other telemetry which may or may not be monitored by the SC, which shall be the responsibility of the responsible hardware manager. It is the responsibility of the hardware manager to analytically or via test determine that all other temperature limits within the component are met as long as the system thermal interface is maintained within limits

(qualification or acceptance). Locations of the temperature limits as defined by the use of telemetry shall be defined by diagram or figure provide in the end item data package (EIDP) prior to delivery of the component to the orbiter assembly in an as-built location. All orbiter-controlled telemetry shall be defined in the Lunar Reconnaissance Orbiter Thermal Hardware Specification (431-SPEC-**TBD**) document or component specific documentation.

2.3 FLIGHT INTERFACE DESIGN TEMPERATURE LIMITS

Table 2-1 below lists the design temperature limits at the SC thermal interface.

Table 2-1a. Spacecraft Interface Temperature Range

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)		
		Op I/F Limit	Qual I/F Limit	Surv I/F Limit
Power	Power Subsystem Electronics S/C I/F at PSE	-10 to +40	-20 to +50	-20 to +50
	S/C I/F at Battery	+10 to +30	+0 to +40	+0 to +40
Attitude Control System (ACS)	S/C I/F at Star Trackers (Radiator I/F temp not Optical Bench temp)	-30 to +50	-35 to +55 Acceptance	-40 to +60
	S/C I/F at Inertial Measurement Unit	-10 to +50	-15 to +55 Acceptance	-20 to +60
	S/C I/F at Reaction Wheels	0 to +50	-10 to +60	-10 to +60
	S/C I/F at Coarse Sun Sensors	-140 to +135**	-145 to +140 Acceptance**	-140 to +145**
Propulsion and Deployables Electronics (PDE)	S/C I/F at PDE	-10 to +40	-20 to +50	-20 to +50
	S/C I/F to Insertion Thrusters (at bracket)	-25 to +60	-25 (survival) to +70 Hot Fire	N/A
	S/C I/F to ACS Thrusters (at bracket)	-25 to +60	-25 (survival) to +70 Hot Fire	N/A
C&DH	S/C I/F at C&DH	-10 to +40	-20 to +50	-20 to +50
	S/C I/F at 9500 Oscillator	-10 to +40	-15 to +45 Acceptance	-20 to +50
S Band Comm	S/C I/F at S-band components	-10 to +50	-20 to +60	-20 to +60
Ka Band Comm	S/C I/F at Ka Baseband Modulator	-10 to +50	-20 to +60	-20 to +60
	S/C I/F at Ka TWT	-10 to +70	-20 to +80	-20 to +80

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)		
		Op I/F Limit	Qual I/F Limit	Surv I/F Limit
	S/C I/F at EPC	-10 to +50	-20 to +60	-20 to +60
Mechanisms	S/C I/F at Gimbal Control Electronics 1 (Hi-Gain)	-10 to +40	-20 to +50	-20 to +50
	S/C I/F at Gimbal Control Electronics 2 (S/A)	-10 to +40	-20 to +50	-20 to +50
Cosmic Ray Telescope of the Effects of Radiation (CRaTER)	S/C at I/F to CRaTER	-30 to +25*	-40 to +35	-40 to +35
Diviner	S/C at I/F to Diviner Instr	-20 to +45	-30 to +55	-35 to +55
	S/C at I/F to remote electronics box	-10 to +45	-20 to +55	-20 to +55
Lyman-Alpha Mapping Project (LAMP)	S/C I/F at base of LAMP's feet	-30 to +30	-40 to +40	-40 to +40
Lunar Exploration Neutron Detector (LEND)	S/C at I/F to LEND	-20 to +40	-30 to +50	-30 to +50
Lunar Orbiter Laser Altimeter (LOLA)	S/C at I/F to Optics Package	-30 to +30	-40 to +40	-40 to +40
	S/C at I/F to Instrument Electronics	-30 to +40	-40 to +50	-40 to +50
Lunar Reconnaissance Orbiter Camera (LROC)	S/C at base of NAC	-30 to +30	-40 to +40	-40 to +40
	S/C I/F at base of WAC	-30 to +30	-40 to +40	-40 to +40
	S/C I/F at base of SCS	-30 to +30	-40 to +40	-40 to +40
Mini RF	S/C I/F at base of antennae's feet	-50 to +50	-60 to +60	-60 to +60
	S/C I/F at base of electronics feet	-10 to +40	-20 to +50	-20 to +50

*Operation in-air will allow the CRaTER operational temperature to be raised to +35 C

** Update will come with latest thermal predicts

Table 2-1b. Component Design Temperature Range

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)		
		Operational	Qualification	Survival
Mechanical	Structure Propulsion Module	-50 to +70	-60 to +80	-60 to +80
	Structure -Avionics Module	-50 to +50	-60 to +60	-60 to +60
	Structure -Avionics to Propulsion	-50 to +50	-60 to +60	-60 to +60
	Structure. Instrument Module	-40 to +50	-50 to +60	-50 to +60
Mechanisms	High Gain Antenna (HGA) Gimbal Motor Housing	0 to +50	-10 to +60	-20 to +60
	HGA Boom	-75 to +75	-85 to +85	-85 to +85
	HGA Dampers	-15 to +35	-25 to +45	-40 to +60
	HGA Rotary Joint (adjacent to Actuators)	-20 to +50	-25 to +55 (acceptance) -30 to +60 (surv)	-30 to +60
	HGA Rotary Joint (adjacent to Hinge)	-30 to +40	-35 to +45 (acceptance) -40 to +50 (surv)	-40 to +50
	Solar Array (S/A) Gimbal motor housing	0 to +50	-10 to +60	-20 to +60
	S/A Dampers	-15 to +35	-20 to +40 Acceptance	-40 to +60
Propulsion System (wetted components only)	Hydrazine Tank 1 +2	+15 to +40	+10 to +45 Acceptance	N/A
	Pressure Tank	+0 to +50	-5 to +55 Acceptance	N/A
	90N Thruster Valves (non-firing)	+10 to +50	+5 to +55 Acceptance	N/A
	22N Thrusters Valves (non-firing)	+10 to +50	+5 to +55 Acceptance	N/A
	All Gas Components upstream of regulator except fill and drain	-40 to +40	-45 to +45 Acceptance	N/A
	All Gas Components downstream of regulator	+10 to +50	+5 to +55 Acceptance	N/A
	All Fill and Drain	+10 to +50	+5 to +55 Acceptance	N/A

SUBSYSTEM	COMPONENT	TEMPERATURE RANGE (°C)		
		Operational	Qualification	Survival
	Gas System Filters	+0 to +50	-5 to +55 Acceptance	N/A
	Liquid Filters	+10 to +50	+5 to +55 Acceptance	N/A
	Pressure Transducers	+10 to +40	+5 to +45 Acceptance	N/A
	Pressure Regulators	+0 to +50	-5 to +55 Acceptance	N/A
	Plumbing Lines	+10 to +50	N/A	N/A
	NC Pyro Valves	-40 to +40	-45 to +45 Acceptance	-60 to +50
K-Band Comm	HGA	-140 to +145	-140 to +145	-170 to +145
	Wave Guide	-50 to +50	N/A	-60 to +60
S-Band Comm	TT&C Omni Antenna	-120 to +80	-125 to +85 Acceptance	-170 to +90
Laser Ranging	Receiver Telescope	-50 to +50	-60 to +60	-75 to +75
	Fiber Optic and Fiber Optic Cable Connectors	-50 to +50	-60 to +60	-60 to +60
Power	Solar Array	-142 to +135 (shunted), +123 (unshunted)	-152 to +145	-195 to +145

2.4 TEMPORAL GRADIENT REQUIREMENTS

Table 2-2 below lists the temporal gradient requirements. Temporal gradient rates shall be evaluated over 6 minute average time periods minimum.

Table 2-2. Temporal Gradient Requirements

SUBSYSTEM	COMPONENT	TEMPORAL GRADIENT (°C/min)
CRaTER	S/C I/F to the Instrument	None
Diviner	Remote Electronics Box Baseplate	1.0
	S/C I/F to Diviner Instrument	None
LAMP	S/C I/F to LAMP Instrument	None
LEND	Instrument Baseplate	2.0
LOLA	Optics Package	None
	Instrument Electronics	None
LROC	NAC (2)	None
	WAC	None
	Instrument Electronics	None
Mini-RF	Antennae	None
	Electronics Box	None

2.5 SPATIAL GRADIENT REQUIREMENTS

Table 2-3 below lists the spatial gradient requirements between mounting feet.

Table 2-3. Spatial Gradient Requirements

SUBSYSTEM	COMPONENT	SPATIAL GRADIENT Between Mounting Feet (°C)
CRaTER	S/C I/F to the Instrument	None
Diviner	S/C I/F to Remote Electronics Box	None
	S/C I/F to Diviner Instrument	None

SUBSYSTEM	COMPONENT	SPATIAL GRADIENT Between Mounting Feet (°C)
LAMP	S/C I/F to LAMP Instrument	None
LEND	Instrument Pkg.#4	None
LOLA	Optics Package	None
	Instrument Electronics	None
LROC	NAC (2)	None
	WAC	None
	Instrument Electronics	None
ACS	Star Cameras	None
COMM	Hi-Gain Gimbals	None
Mini-RF	Antennae	None
	Electronics Box	None

2.6 TURN ON TEMPERATURE AND SURVIVAL

When powered “OFF”, each component shall be capable of surviving indefinitely when its temperatures are within the qualification survival limits without damage or permanent performance degradation.

All components shall also survive indefinitely, without damage or permanent performance degradation, if powered “ON” anywhere from the minimum survival temperature to 10°C above the maximum operating temperature.

For components that are conductively coupled to the SC, when powered “OFF”, the SC Thermal Control System shall maintain the instruments within the design survival temperature limits. If necessary, the SC will use survival heating as described in Section 3.2.6 to maintain the low limit.

2.7 ALLOCATION OF SPACECRAFT MONITORED TEMPERATURE SENSORS

Table 2-4 specifies the number of SC monitored temperature sensors allocated to each component. The telemetry types listed only apply to the column in the table labeled “Number of Telemetry Points”. The ‘Internal Box Telemetry’ sensors can be alternative telemetry types since they may be read by alternative avionics. The current baseline for temperature sensors is 2252 ohms **311P18-02-A-101** or Platinum Resistance Thermistor (PRT) (**0118MF2000AC + 00118-1009-2003 (36in)**), 2000 ohms @ 0°C) as specified by the LRO Thermal Systems Lead. The thermistor/PRT shall be capable of being read over the all temperature ranges specified. The

thermistor sensors shall be accurate within 1.5 degree C from -40 to +75 C. The PRT sensors shall be accurate within 3.0 degree C from -170 to +145 C. The thermistor electrical interface shall be per the relevant electrical ICD and that the physical placement of each thermistor is per the relevant thermal ICD.

Table 2-4. Telemetry Point Details

Subsystem	Details	MAC Thermistors	MAC PRTs	Other Internal Telemetry
Mechanical		29	0	
Comp. Propulsion Module	Rationale: Need to understand temperature of HP and LP modules. Need to know driving sources of propulsion Module if problem arises.			
	L/V I/F at S/C I/F	1		
	HPCM	1		
	LPCM	1		
	Outer Structure of S/C bus +/- Z panel	2		
	Outer Structure of S/C bus +/- Y panel	2		
	AP Radiators	4		
	Battery Radiator	2		
Comp. Instrument Module	Rationale: Need to do in-flight STOP if pointing problem.			
	Interfaces with Structure +Y	5		
	Interfaces with Structure -Y	3		
	Zenith Side	5		
	Nadir Side	3		
Mechanisms		6	0	
HGA Gimbals and Rotary Joints				
HGA Boom				
HGA Release & Deploy				
	Deployment Hinge/Rotary Joint	1		
	Damper	1		
	Sep Nut Release point			
S/A Gimbals				2 PRTs (GCE2)
S/A Boom				
S/A Release & Deploy				
	Deployment Hinge (2)			
	Dampers (2)	2		
	Sep Nut Release point (2)			

Subsystem	Details	MAC Thermistors	MAC PRTs	Other Internal Telemetry
	S/A GCE 2 Box	1		1 PRTs (GCE2)
	HGA GCE 1 Box	1		1 PRTs (GCE1)
Thermal		71	2	
Thermal Control Heaters (Redundant)	Rationale: If thermistor fails, circuit fails	22 (active control)		
Fuel Tank Heaters (2 Tanks tanks)	Rationale: Need be able to turn off a thermostatic heater circuit if problematic. Fuel temperatures must be controlled.	8		
Pressurant Tank Heaters	"	2		
Fuel Line Heaters (Redundant)	"	10		
20# Valve heaters (Redundant)	"	8		
5# Valve Heaters (Redundant)	"	16		
S/A Gimbal T-Stat control at each heater	Rationale: Monitor Each Heater Circuit in Survival	2		
High Gain Gimbal T-Stat control at each heater	Rationale: Monitor Each Heater Circuit in Survival	2		
LEND (on S/C)	Rationale: Monitor Heater Circuit to ensure heaters	1		
CRaTER (on S/C)	Rationale: Monitor Heater Circuit to ensure heaters		1	
Laser Receiver Telescope			1	
Power		1	2	
PSE				7 Thermistors (PSE)
Battery		1 @ S/C I/F		2 PRTs (PSE)
S/A Cells/Cover Glass/CSS				4 PRTs (PSE) 2 PRTs (GCE2)
S/A Substrate (CSS monitor)	Rationale: Monitor CSS temperature for ACS		2	
ACS		8		
PDE	Monitor turn-on Temp	1		
Star Trackers	Rationale: Monitor Htr Circuit	2		TBD
Inertial Measurement Unit	Monitor turn-on Temp	1		
Reaction Wheels	Monitor turn-on Temp	4		4 (RWA) elec

Subsystem	Details	MAC Thermistors	MAC PRTs	Other Internal Telemetry
Coarse Sun Sensors	Monitor turn-on Temp		See S/A	
Propulsion			12	
Hi-Temperature Cat Bed PRTs			12	
Hydrazine Tank			See Thermal	
Pressure Tanks			See Thermal	
20# Thrusters			See Thermal	
5# Thrusters			See Thermal	
HPCM			See Mechanical	
LPCM			See Mechanical	
C&DH		3		
Oscillator	Internal Chassis	1 (30 kohm)		
	Oscillator Oven	1 (30 kohm)		
C&DH Box	Survival Heater	1		11 (C&DH with 5 internal only spares)
S Comm		4		
TT&C	TT&C XPDR Stack (xmit)	1		TBD
	TT&C XPDR Stack (Rec)	1		
	TT&C Omni Antenna	2		
Ka Comm		4		
	Ka Baseband Modulator	1		
	Ka EPC	1		
	Ka TWTA	2		
	Ka Bandreject Filter			
	WG-34 Ka Band Waveguide			
	High Gain Antenna			3 PRTs (GCE1)
Electrical				
	Harness			
	Total Instruments	22	1	
CRaTER	INST #1		1	
	Telescope		1	

Subsystem Diviner	Details	MAC Thermist ors	MAC PRTs	Other Internal Telemetry
		5		
	OBA	1		
	Az Actuator	1		
	Elev Actuator	1		
	DREB	1		
	Yoke	1		
LAMP	INST #3	1		
	LAMP Reference Point	1		
LEND	INST #4	2		
	LEND Elec	1		
	LEND Detector	1		
LOLA	INST #5	3		
	Laser Bench	1		
	Receiver Tube Flange	1		
	PCA Sidewall	1		
LROC	INST #6	8		
	SCS FPGA	1		
	WAC Focal Plane	1		
	NAC-L FPGA	1		
	NAC-L Focal Plane	1		
	NAC-L Metering Structure	1		
	NAC-R FPGA	1		
	NAC-R Focal Plane	1		
	NAC-R Metering Structure	1		
Mini-RF	Tech Development	3		
	S/C I/F to Antennae	0		
	Electronics side of thermal interface (1 per box)	3		
	S/C SUBTOTAL	126	17	
	INSTRUMENTS TSUBTOTAL	22	1	
	TOTAL	148	18	
	Spares	3	2	4 PRTs GCE1 3 PRTs GCE2
Total Allowable	171 PRTs and Thermistors			

3.0 THERMAL POWER

3.1 GENERAL HEATER CIRCUIT REQUIREMENTS

Sizing of operational and survival heater capacity shall be based on 70% duty cycle at 27 volts (V) bus voltage and cold case thermal conditions. Heater elements must be capable of operating over the voltage range of $28 \pm 7V$.

Each component shall provide space for mounting thermostats, heaters and temperature sensors. Heaters, if Kapton film heaters, shall comply with NASA GSFC S311-P-079. Heaters, if Vishay Dale Ohm, shall comply with Military/Established Reliability, MIL-R-39009 Qualified, Type RER, R Level, Aluminum Housed, and be Standard (ERH). Mechanical Thermostats, if used, shall comply with NASA GSFC S311-641.

Watt densities of the operational and survival heaters shall be appropriate for the type of heater and bonding method. Watt densities (calculated at the maximum voltage) above 0.16 Watts per centimeters squared (W/cm^2) (1.0 Watts per inch squared [W/in^2]) shall be approved by the GSFC LRO Thermal Engineer Lead and may require (if a Kapton heater) bonding with Stycast 2850FT and aluminum over-taping up to $1.24 W/cm^2$ ($8.0 W/in^2$).

3.2 THERMAL DISSIPATED POWER PER MISSION MODE

Thermal dissipative power is different from electrical power allocation due to the need to identify the location where the electrical power is dissipated. The purpose for this section is to handshake with the responsible hardware manager what inputs are used in the overall thermal model during which mission mode. Embedded into thermal dissipative power is the need to analyze the worst case orbit average power both high and low even if it is just for one orbit. Table 3-1 shows power dissipations by component without margin. It also details all mission modes that the components shall experience including pointing and SC configuration.

3.3 SPACECRAFT CONTROLLED THERMAL CONTROL HEATER POWER

The SC shall control several heater power circuits. These heater power circuit sizes and locations are detailed in the Lunar Reconnaissance Orbiter Thermal Hardware Specification (431-SPEC-**TBD**) document. This specification provides details with respect to orbit average heater dissipation and peak power dissipation.

3.3.1 Instrument Operational Heater Power Description

This switch is intended to service operational heaters in the instrument module. Nominally, the heaters will be located at the component. The sizing of the heaters will be designed such that all components are maintained thermostatically at the low end of the operational temperature range regardless of the actual power that the component is dissipating during different regular operational modes. In the cold case, this heater power is necessary to offset the losses from the instrument to the environment and the variation in power based on different operational modes.

In the hotter Beta angles, this heater power will be reduced and eliminated as the environment warms up. When the instruments are not operating, this heater switch will be switched off to preserve power such as during the lunar eclipse.

3.3.2 Spacecraft Operational Thermal Control Heat Power Description

This switch is intended to service SC components regardless of where they are located (propulsion module, Avionics deck, or instrument module). This switch feeds the separately wired thermostatically controlled operational heaters. These heaters will also provide some heater power to components during cold operational periods that prevent components from exceeding their cold operational temperature due to losses from those components to the cold environment. These SC components will be ones that may be switched off during lunar eclipse or safe hold modes of operation. This heater circuit may be switched off during lower power modes such as lunar eclipse or safe hold and therefore should only service components that either needs tighter stability during certain fully operational modes or components that are switched off automatically during lunar eclipse or safe hold conditions. Examples of these components are the Star Trackers operational, Hi-Gain gimbal operational, and Traveling Wave Tube Amplifier (TWTA) operational heaters.

3.3.3 Tight Bandwidth Command and Data Handling and Software Controlled Heater

An additional five tight temperature control in C&DH and six in the PSE circuits have been allocated per Table 3-2a and Table 3-2b. This allows tailoring of these five thermal control points to fine tune thermal control. The intention of these heater circuits is to resolve thermal control/stability issues that arise later in the program.

Table 3-2a. Five Tight Control Heaters Powered by C&DH

Heater # / Max Amp	COMPONENT	Orbit Avg Power at 27 V/Peak Power at 35 V
1/5 amp	LEND Radiator	20
2/2 amp	AP VCHP#1	8
3/2 amp	AP VCHP#2	8
4/2 amp	AP VCHP#3	8
5/2 amp	AP VCHP#4	8

Table 3-2b. Six Tight Control Heaters Powered by PSE

Heater # / Max Amp	COMPONENT	Orbit Avg Power at 27 V/Peak Power at 35 V
1/5 amp	Op Bench #1 (NAC 1 I/F)	10
2/2 amp	Op Bench #2 (NAC 1 I/F)	10
3/2 amp	Op Bench #3 (LOLA OTA I/F)	10
4/2 amp	Op Bench #4 (WAC I/F)	10
5/2 amp	NAC #1 Metering Structure	13
6/2 amp	NAC #2 Metering Structure	13

3.3.4 Propulsion System Heaters Primary and Redundant Description

This switch is intended to service the propulsion system heaters and is redundant. The heaters will be located on the thruster valve heaters, propulsion lines, propulsion tanks, and the propulsion pressurization tank. These heaters shall be enabled during all mission modes as they are designed to prevent the Hydrazine from freezing.

3.3.5 Deployment Heaters Description

This switch controls operational thermostatically controlled heaters at the deployment mechanisms and hinges to ensure deployment within the operational range. These heaters will be switched off after deployment to preserve heater power.

3.3.6 Essential Heater Description

These unswitched services are designed to prevent components that are always enabled (essential) during all mission modes from exceeding the lower operational temperature limit and to prevent SC components that may be switched off from exceeding their lower survival temperature limit. The two thermostatically controlled heater circuits shall be offset in setpoint so that their operation can be verified separately during observatory thermal vacuum testing and to prevent the higher peak power which would result if the two redundant thermostats sets were to close at the same time. Examples of heaters on this circuit would be: C&DH operational heaters, battery operational heaters, S-Band operational heater, and Ka band transmitter survival heaters. Operational heaters for the Gyro and RWAs will be on this circuit. Also included are survival heater for avionics that require them in non-operational modes.

Instrument Survival Heaters Description

This service will primarily service the instruments and instrument module to maintain all the instruments within their cold survival temperature. These heaters shall be wired out from the common service to two separate heater services located on the instruments. It is expected that these services will be thermostatically controlled and may be located on the instruments themselves. This bus also includes survival heater for the de-coupled optical bench and S/C interface heater control for LEND and CRaTER.

3.4 SPACECRAFT HEATER ALLOCATION

The heater allocation is per the Technical Resource Allocations Specification 431-SPEC-000112.

3.5 INSTRUMENT HEATER ALLOCATION (WIRED TO SPACECRAFT SWITCH)

The instrument heater power allocation on the SC Instrument Operational bus is outlined in Table 3-3 and described in Section 3.3.1. The power shown is at 27V and is the size of the heater with the General Environmental Verification Standards (GEVS) margin 70% duty cycle (i.e., the powers below are an orbit average with a 70% duty cycle not what the power would be if the heaters were at 100% duty cycle because by design they will not exceed 70%). All services shall be thermostatically controlled at the instrument. The SC is providing no active control. Heaters shall be NASA GSFC S311-079 Kapton film heaters or Vishay Dale Ohm heaters (MIL-R-39009 Qualified) approved by LRO Thermal Systems Lead. Mechanical thermostats shall be NASA GSFC S311-641 qualified and have an approved circuit design by the LRO Thermal Systems Lead.

Table 3-3. Instrument Control Heater Power Allocations on the SC Instrument Operational Bus

INSTRUMENT	HEATER POWER (W)		
	Operational	DeContam.	Survival
CRaTER	Sized by S/C	None	Sized by S/C
Diviner Instrument	Provided thru Instrument Main Power Feed	None	35.
Diviner Electronics (DREB)	Sized by S/C	None	Sized by S/C
LROC NAC1 Metering Structure	Provided by S/C Software Control <13 W	Provided separately via non-thermal switch	4

INSTRUMENT	HEATER POWER (W)		
	Operational	DeContam.	Survival
LROC NAC2 Metering Structure	Provided by S/C Software Control <13 W	Provided separately via non-thermal switch	4
LROC NAC #1 Adapter Plate	4	None	None
LROC NAC #2 Adapter Plate	4	None	None
LROC NAC #1 Elec	None	None	5
LROC NAC #2 Elec	None	None	5
LROC WAC	4	Provided separately via non-thermal switch	5
LROC SCS	2	None	4
LAMP	7	Dissipated thru LAMP main power feed	10
LEND	Sized by S/C	None	Sized by S/C
LOLA Combined	30.5	None	50
Mini-RF	None	None	None

3.6 INSTRUMENT HEATER ALLOCATION (CONTROLLED BY COMPONENTS/ INSTRUMENTS)

The instrument heater power allocation drawn from the internal instrument power bus is outlined in Table 3-4 as described in the individual instrument ICDs. The power shown is at 27V and is the size of the heater with GEVS margin 70% duty cycle. The power from these heaters will come directly out of the main instrument feeds and will only be operational when the instruments are turned on. Heaters shall be NASA GSFC S311-079 Kapton film heaters or Vishay Dale Ohm heaters (MIL-R-39009 Qualified) approved by LRO Thermal Systems Lead. Mechanical thermostats shall be NASA GSFC S311-641 qualified and have an approved circuit design by the LRO Thermal Systems Lead.

**Table 3-4. Instrument Control Heater Power Allocations
Drawn from the Internal Instrument Power Bus**

INSTRUMENT	HEATER POWER (W)	
	Operational	DeContam.
CRaTER	None	None
Diviner	6	None
LROC NAC1	None	None
LROC NAC2	None	None
LROC WAC	None	None
LROC SCS	None	None
LAMP	None	1.4 W
LEND	4 max	None
LOLA Elec	None	None
LOLA Op Bench/Laser	None	None
LOLA TEC	3 max	None
Total	13	1.4

4.0 MULTI-LAYER INSULATION BLANKETS

4.1 OUTER BLANKET COATING

All exterior facing Multi-Layer Insulation (MLI) blankets in the avionics and instrument module area shall have a Black Germanium Kapton in outer coating unless approved by the LRO Thermal Systems Engineer Lead. There will be blankets in the propulsion module area that will need metallic shield outer layers and may use 3 mil Kapton.

4.2 MULTI-LAYER INSULATION BLANKET GROUNDING

All blankets shall be grounded in accordance with the Lunar Reconnaissance Orbiter Electrical Systems Specification (431-ICD-000008).

4.3 MULTI-LAYER INSULATION BLANKET DOCUMENTATION

All component MLI blankets shall have their location and shape documented in component as-built ICDs. All thermal subsystem MLI blankets shall be documented in the Lunar Reconnaissance Orbiter Project Electrical Systems Specification (431-SPEC-000008).

4.4 ATTACHMENT OF MULTI-LAYER INSULATION BLANKETS

All exterior MLI blankets shall be mechanically constrained at least at one point or mechanically captured by another blanket or mechanical component.

5.0 THERMAL ANALYSIS

5.1 ENVIRONMENTAL CONDITIONS

5.1.1 Thermal Conditions

The LRO environment is listed in Tables 5-1 and 5-2 below. MLI blankets shall be analyzed using an effective ε^* equal to 0.005 or 0.03, case specific, that yields the worst case in the bounding thermal cases.

Table 5-1. LRO Solar Constant and Albedo Factor

PARAMETER	Cold	Hot
Solar Constant	1280 W/m ²	1420 W/m ²
Albedo Factor	0.06	0.13

Table 5-2. LRO Lunar Infrared

ORBIT POSITION (°)	Beta θ° (W/m ²)	
	Hot	Cold
0 (sub-solar)	$(1335-5)*1*\text{COS}(\theta) + 5$	$(1114-5)*1*\text{COS}(\theta) + 5$
30	$(1335-5)*0.866*\text{COS}(\theta) + 5$	$(1114-5)*0.866*\text{COS}(\theta) + 5$
60	$(1335-5)*0.5*\text{COS}(\theta) + 5$	$(1114-5)*0.5*\text{COS}(\theta) + 5$
90	5	5
120	5	5
150	5	5
180	5	5
210	5	5
240	5	5
270	5	5
300	$(1335-5)*0.5*\text{COS}(\theta) + 5$	$(1114-5)*0.5*\text{COS}(\theta) + 5$
330	$(1335-5)*0.866*\text{COS}(\theta) + 5$	$(1114-5)*0.866*\text{COS}(\theta) + 5$
360 (sub-solar)	$(1335-5)*1*\text{COS}(\theta) + 5$	$(1114-5)*1*\text{COS}(\theta) + 5$

5.1.2 Payload Fairing Ascent Pressure Profile

All MLI blankets and thermal hardware shall be built so that the rapid launch depressurization does not detach any thermal blankets or hardware (see Figure 5-1).

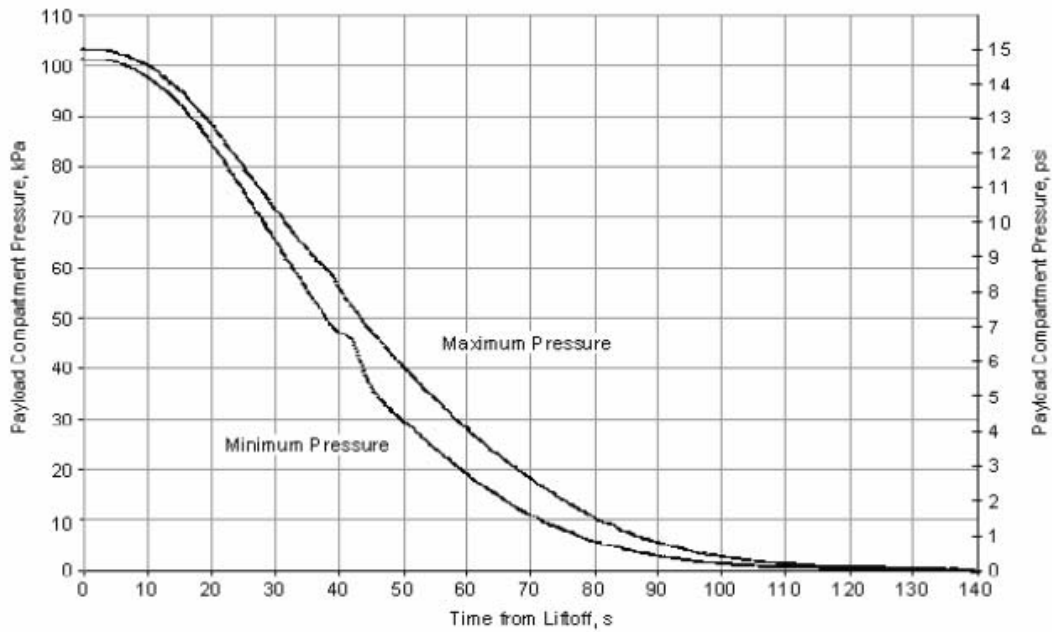


Figure 5-1. Atlas V EELV-Like Fairing Pressure

5.2 THERMAL COATINGS

Table 5-3. LRO Thermal Coatings

DESCRIPTION	COLD		HOT 14 mo. (5 yr.)		SPEC.	
	α_s	ϵ_H	α_s	ϵ_H	SOL	IR
Coatings						
Black Anodize Aluminum	0.7	0.82	0.86	0.78		
Clear Anodize	0.27	0.82	0.45	0.69		
Irridite Aluminum	0.10	0.19	0.57	0.06		
Z307 Conductive Black	0.95	0.89	0.97	0.85		
MSA94B Conductive Black	0.94	0.91	0.96	0.87		

DESCRIPTION	COLD		HOT 14 mo. (5 yr.)		SPEC.	
	α_s	ϵ_H	α_s	ϵ_H	SOL	IR
Z306 Black Paint	0.94	0.89	0.95	0.85		
Z93P White Paint	0.17	0.92	0.25 (0.36)	0.87		
NS43C Conductive White	0.20	0.91	0.26 (0.37)	0.87		
NS43G White Paint	0.26	0.90	0.32 (0.43)	0.86		
Vapor Deposited Aluminum	0.08	0.05	0.10	0.03	0.98	0.98
Vapor Deposited Gold	0.19	0.03	0.21	0.02		
BR127 Black Primer	0.96	0.85	N/A	0.81		
ITO/A276 (Back of Solar Array)	0.27	0.87	0.30 (0.35)	0.83		
A276 (Omni Antenna)	0.26	0.87	0.60 (0.60)	0.83		
Films & Tapes						
Kapton, 3-mil/VDA backing	0.45	0.80	0.51 (0.60)	0.76	0.75	
OSR/ITO Pilkington, 5-mil	0.08	0.80	0.15 (0.23)	0.78	1.0	
ITO/Kapton/VDA 3 mil	0.46	0.80	0.51 (0.62)	0.76	0.75	
Black Kapton, 3-mil	0.91	0.81	0.93	0.78		
Germanium Black Kapton	0.49	0.81	0.51	0.78		
Silver Teflon ITO 5 mil (note that this is fragile and will require frequent replacement)	0.09	0.78	0.28 (0.37)	0.73	1.0	
2 mil with tailored Dielectric SS Outer Blanket Layer (Thruster)	0.07	0.54	0.14	0.45		
Miscellaneous						
Solar Cell Triple Junction	0.86	0.87	0.90	0.77	1.0	---
M55J Composite, Bare	0.90	0.79	0.93	0.75		

DESCRIPTION	COLD		HOT 14 mo. (5 yr.)		SPEC.	
	α_S	ϵ_H	α_S	ϵ_H	SOL	IR
K1100 Composite, Bare	0.88	0.73	0.88	0.69		
Fused Silica	<0.03	0.79	0.10	0.75		
BK7 Optical Glass	0.05	0.82	0.10	0.78		
Sapphire Lens	TBD	TBD	TBD	TBD		
Internal Fuel Line	1.0	0.15	1.0	0.15		
Machined Stainless Steel	0.39	0.18	0.47	0.14		
Hafnium	0.47	0.50	0.47	0.50		
Titanium Burnt	0.47	0.50	0.47	0.50		
Tiodized Titanium	0.74	0.23	0.86	0.73		

5.3 HOT AND COLD BIAS OF POWER

Prior to the active measurement of operational power in a flight-like environment, the thermal design shall be able to handle a variation (due to uncertainty) in each mode power on constant power components. Powers to use in hot case and cold case shall be as follows: maximum power allocation in hot case, cold case minimum power dissipation current best estimate should be analyzed.

5.4 MISSION MODES

All components shall meet the appropriate survival or operational limits (component and mission mode specific) per Table 3-1 during all mission modes.

5.5 THERMAL MODEL MARGIN

Prior to flight, 5°C is the minimum required margin for model predictions with respect to Flight Operational Limits, except for heater controlled elements that demonstrate a maximum 70% heater duty cycle.

5.6 THERMAL MODELING SCOPE

The thermal modeling scope for LRO will be different than for other planetary mission's conventional wisdom. Transient analysis will be required to assess hot and cold cases. SC pointing tolerances may drive safe hold cases. Steady sun angles at high Beta angles may drive spatial gradient requirements. The responsible hardware manager shall examine all relevant

environments assuming worst case pointing uncertainties in order to determine bounding thermal cases using Table 3-1 and direction as requested from the LRO Thermal Systems Lead.

5.7 THERMAL ANALYSIS DOCUMENTATION

All thermal analysis reports shall clearly outline all assumptions or source of assumptions. They shall detail the modeling technique used, details on the model, graphics and tables showing the temperature results versus requirements and discussion of what the results are sensitive to. It shall be clear what limitations the current analysis is subjected to and what future analyses are planned.

6.0 COMPONENT AND ORBITER INTEGRATION AND TEST

The components and orbiter shall be tested in the bounding thermal cases in thermal vacuum. The target temperatures shall be specified as a result of a test model analysis. All thermal hardware shall comply with the Lunar Reconnaissance Orbiter Mechanical Systems Specification (431-SPEC-000012).

6.1 COMPONENT THERMAL CYCLING REQUIREMENT

All components must be thermally cycled in a thermal vacuum chamber rather than in an air filled chamber. All components shall be flight like blanketed and cycled 8 times with the thermal interface held at the qualification temperatures listed above at the thermal interface. Durations shall be as recommended in GEVS: components 4 hours, instruments 12 hours. If the component is sensitive to orbit transience, component performance shall be monitored during hot to cold transitions at a rate that a flight like orbit average case might experience. Thermal Vacuum requirement can only be waived through approval of the LRO Thermal Systems Lead.

6.2 MODEL DOCUMENTATION

The Reduced Geometric Math Models (RGMMs) and Reduced Thermal Math Models (RTMMs) delivered to GSFC shall be accompanied by appropriate model documentation as specified in the Lunar Reconnaissance Orbiter Thermal Math Model Requirements (431-RQMT-000092) document.

6.3 COMPONENT THERMAL TEST MODEL

All thermal tests shall be Thermal Synthesizer System (TSS)/System Improved Numerical Differencing Analyzer (SINDA) modeled prior to starting the test to derive target temperatures. Target temperatures shall achieve heat flows and effective sink temperatures that closely resemble the flight environment. An analysis report shall be issued which outlines the derivation of the target temperatures. This analysis report should outline all cases that will be assessed in thermal vacuum (i.e. hot case steady state, hot transient, cold steady state, survival, etc.)

6.4 COMPONENT THERMAL TEST DOCUMENTATION

All final thermal qualification test plans shall be approved by the LRO Thermal Systems Lead. Target temperatures and overall test setup shall be discussed with the LRO Thermal Systems Lead.

6.5 THERMAL MODEL CORRELATION

All models shall be correlated within 2°C of every telemetry point with the thermal test model. The thermal test model shall then be reintegrated into the flight model.

6.6 REDUCED MODEL

Reduced component models shall be made available to the thermal team 30 days before the Preliminary Design Review (PDR), Critical Design Review (CDR), Pre-Environmental Review (PER), and delivery to Orbiter Integration and Test (I&T). Models requested earlier than this requirement shall be used to pass back to components as bounding system reduced models for component reviews and therefore their delivery dates shall be based on 45 days before the first component review. These models shall utilize the latest known power levels and mechanical configuration. The models shall be correlated with any qualification testing. The reduced model shall be delivered in accordance with the Lunar Reconnaissance Orbiter Thermal Math Model Requirements (431-RQMT-000092).

6.7 IN-AIR THERMAL CONTROL

All instruments shall be capable of operating within an ambient air temperature of $20\pm 5^{\circ}\text{C}$ without degrading instrument performance. No active cooling shall be provided during instrument operation with or without blanket covering. Allowance in the instrument blanket design may be utilized to open higher heat flux areas of the instrument to the surrounding ambient air, but the blanket design shall accommodate opening and closing without blanket damage.

6.8 ORBITER THERMAL VACUUM/BALANCE LEVELNESS AND ORIENTATION REQUIREMENTS

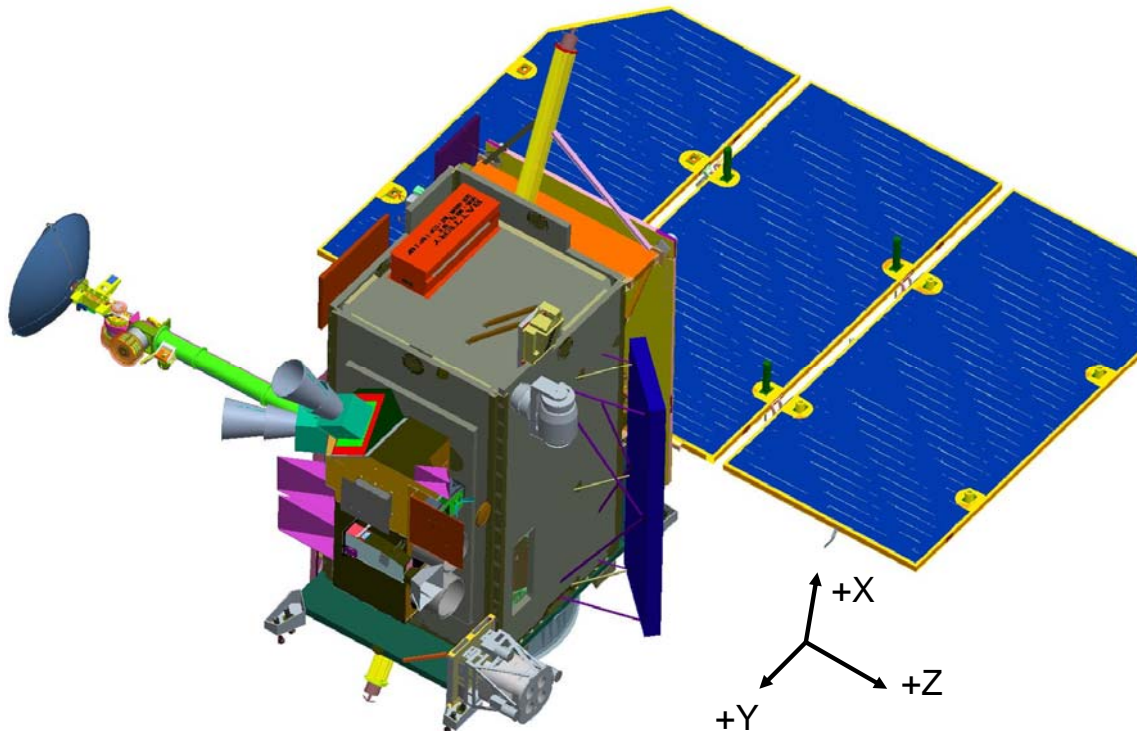
All instruments shall be capable of operating within a thermal vacuum chamber with flight like thermal environment based on the instrument reduced models provided. The horizontal plane will be the X and Y axes with instrument viewing nadir down. There is no known sensitivity to the gravity vector for proper operation during this test of any non-thermal component. Heat Pipes, if they are utilized, will require no more than a $\pm 0.1^{\circ}/70^{\circ}$ tilt in any one location from the horizontal plane.

6.9 LUNAR RECONNAISSANCE ORBITER COORDINATE SYSTEM

The LRO mechanical and thermal coordinate system is shown in Figure 6-1. Unless otherwise noted, this document shall refer to the LRO coordinate system.

6.10 TEST HEATERS

During Orbiter thermal vacuum (TVAC) testing, the configuration of the Orbiter in the vicinity of each component may not be flight like due to placement heater panels and cold plates. The effective sink temperature for some components may be colder than during the mission. Each responsible hardware manager shall anticipate, to the extent possible, such possibilities and provide test heaters in coordination with the LRO Thermal Systems Lead. Prior to component I&T the responsible hardware manager in coordination with the LRO Thermal Systems Lead shall make a determination of whether test heaters will be required.



In such cases, the responsible hardware manager shall supply their own test heaters, cabling and means of control (**TBR**). Any such heaters shall be mounted on the component, not the SC. The component team shall install and control any such test heaters, as needed, to maintain the temperatures of the instrument within the survival range during TVAC.

Heater leads should be of sufficient length to allow connection to test chamber heater harnesses.

6.11 TEST SENSORS

Test sensors required to verify proper operation of the component during orbiter thermal vacuum testing shall be installed prior to delivery of the component. These sensors shall be identified on as-built drawings using orbiter approved test sensors. A plan shall be also submitted to remove some or all of these sensors before flight. The test sensors that may be read at orbiter thermal vacuum testing will be limited or reduced by the LRO Thermal Systems Lead to meet the test setup requirements.

Appendix A. Abbreviations and Acronyms

Abbreviation/ Acronym	DEFINITION
ACS	Attitude Control System
°C	Degrees Centigrade
C&DH	Command and Data Handling
CBE	Current Best Estimate
CCB	Configuration Control Board
CCR	Configuration Change Request
CDR	Critical Design Review
CM	Configuration Management
CMO	Configuration Management Office
CRaTER	Cosmic Ray Telescope of the Effects of Radiation
Diviner	Diviner Instrument
ELV	Expendable Launch Vehicle
EPC	Electrical Power Conditioner
EVD	Engine Valve Driver
GEVS	General Environmental Verification Standards
GSFC	Goddard Space Flight Center
HGA	High Gain Antenna
HKIO	House Keeping Input Output
Htrs	Heaters
I&T	Integration and Test
I/F	Interface
ICD	Interface Control Document
IR	Infrared
IMU	Inertial Measurement Unit
Km	Kilometer
LAMP	Lyman-Alpha Mapping Project
LEND	Lunar Exploration Neutron Detector
LOLA	Lunar Orbiter Laser Altimeter
LROC	Lunar Reconnaissance Orbiter Camera
LRO	Lunar Reconnaissance Orbiter
LVPC	Low Voltage Power Converter
Max.	Maximum
Min.	Minimum
MLI	Multi-Layer Insulation
Mo.	Months
MTG	Mounting
N/A	Not Applicable
NAC	Narrow Angle Camera

A-1

CHECK WITH LRO DATABASE AT:
<https://lunarngin.gsfc.nasa.gov>
 TO VERIFY THAT THIS IS THE CORRECT VERSION PRIOR TO USE.

Abbreviation/ Acronym	DEFINITION
NASA	National Aeronautics and Space Administration
NC	Normally Closed
OP	Operational
PDE	Propulsion and Deployable Electronics
PDR	Preliminary Design Review
PER	Pre-Environmental Review
PRT	Platinum Resistance Thermistor
PSE	Power Subsystem Electronics
Psi	Pounds per square inch
Pts	Points
Pwr	Power
RF	Radio Frequency
RGMM	Reduced Geometric Math Model
RTMM	Reduced Thermal Math Model
RWA	Reaction Wheel Assembly
S/A	Solar Array
SBC	Single Board Computer
SC	Spacecraft
SCS	Sequencing and Compressor System
Sec.	Seconds
SINDA	Systems Improved Numerical Differencing Analyzer
SOL	Solar
Spec.	Spectularity
SSR	Solid State Recorder
STS	Space Transportation System
TBD	To Be Determined
TBR	To Be Reviewed
TSS	Thermal Synthesizer System
TT&C	Telemetry Tracking and Control
TWTA	Traveling Wave Tube Amplifier
USB	Universal System Bus
VDA	Vapor Deposited Aluminum
W	Watt
w/o	Without
W/cm ²	Watts per centimeter squared
W/in ²	Watts per inch squared
W/m ²	Watts per meter squared
WAC	Wide Angle Camera
XPDR	Transponder
V	Volt(s)

